

TIM-GAP GEL PAD

Cool it Right

DATA SHEET

Thermally Conductive Insulating Pad

Descriptions

TIM-GAP GEL PAD is very soft, highly conformable thermal interface pad designed to meet industry's rapidly growing need for interface material with high thermal conductivity and conformability for low stress applications. **TIM-GAP GEL PAD** is designed with flame retardant silicone polymer filled with special organic substance and thin polyester reinforcement for a wide range of applications, **TIM-GAP GEL PAD** is a clean, production friendly and efficient alternative to mica, ceramics or grease and will provides superb protection against damage due to deformation as well as shock or vibration.

Key Features

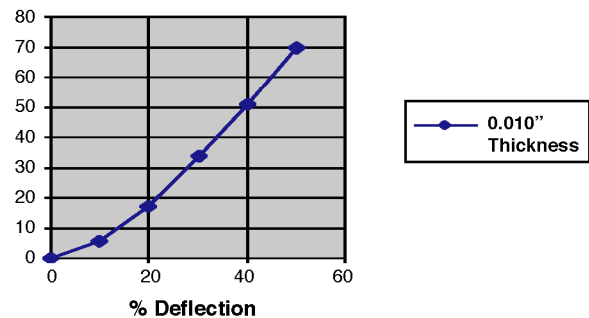
- High Thermal Conductivity
- Electrically Insulating
- Smooth and highly compliant surface
- Eliminates the mess of grease
- Clean and easy to apply
- Will not dry out, high temperature resistance
- No out gassing under vacuum
- Re-workable/Clean release from device

Applications

- Interface for discrete semiconductors requiring low pressure or spring clamp mounting
- Chip burn-in, chip testing fixtures, DC-to-DC converters, IGBT and hot and cold plates.
- Medical devices
- Between CPU and Heat Spreader
- Consumer electronics
- Industrial controls

PHYSICAL PROPERTY	TEST METHOD	GEL PAD
Type		Silicone
Color	Visual	Dark Gray
Operating Temp. range °C		-40 to 150
Thickness. (inch)		0.010
Tensile Strength. MPa	ASTM D-412	11
Hardness. Shore 00	ASTM D-2240	49
Thermal Conductivity. W/m ² °k	ASTM D-5470 Modified	1.6
Thermal Resistance. °C-inch ² /W	ASTM D-5470 Modified	0.35
Breakdown Voltage	ASTM D-149	5000
Volume Resistivity, Ohm-cm	ASTM D257	10 ¹⁵
Available thickness, inch.		0.010

Pressure vs Percent Deflection



Availability

- **TIM-GAP GEL PAD** is available in die-cut, sheet or roll. Materials are available standard and/or special shape and size. This material can apply with "pick & place" and other types of high volume production dispensing equipment.
- Tooling charges vary depending on tolerances and complexity of the part
- **TIM-GAP GEL PAD** materials are available with or without adhesive for easy handling and installation in standard or complex assemblies.



Disclaimer: All data given here is offered as a guide to the use of these materials and not as a guarantee of their performances. The user should evaluate their suitability for own purposes. Properties are typical and should not be used in preparing specifications. Statements are not be construed as recommendations to infringe any patent